Test Capabilities

- **8 On-wafer Auto Probe Stations**
  - **5 Electroglas 2001X auto probers**
  - **2 Cascade Microtech Probers**
  - **1 Karl Suss Prober**
- **5 RF test and Characterization systems**
  - **Wafer level production OIP3 testing**
  - **HP8722D Network Analyzer/ICCAP (.05 – 40 GHz): Insertion and return loss, Isolation, s-parameters, DC parameters, device modeling**
  - **HP8510C Network Analyzer (.01 – 26.5 GHz): Insertion and return loss, isolation s-parameters, device model**
  - **Maury Microwave (0.8 – 18 GHz): Source/load pull, noise parameters, IP3, harmonics, ruggedness**
  - **Focus Tuners (6 – 40 GHz): Source/load pull, noise parameters, IP3, harmonics, ruggedness**
- **3 DC test systems**
  - **PCM and 100% on-wafer die testing**

Electroglas On-wafer Characterization Probe Station

- Electroglas 2001X Automatic Probe Station
- HP Network Analyzer 8510C (10 MHz – 26.5 GHz)
- HP Synthesized Sweeper 83631B
- Test capabilities include:
    - S parameters measurements (insertion loss, return loss, isolation, etc.)
    - Small signal modeling
    - Large signal modeling

On-Wafer Automated Test Systems

Two Production On-Wafer Automated Test Stations

- ReedHolm Semiconductor Parametric Tester and ElectroGlas Automated Probe Station
- High-speed PCM tests include device DC parameters, material and process parameters
- High-speed DC testing for product die screening
- Test speed: 10 ms per parameter, 0.1 sec per die stepping

100% Die Test and Inking Capability

WCDMA PA

# Parameters	37
# Total Dies	4950
# Fails	115
# Passes	4835
Die Yield	97.7%